

FDP20N50F / FDPF20N50FT

N-Channel MOSFET, FRFET

500V, 20A, 0.26Ω

Features

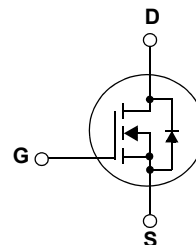
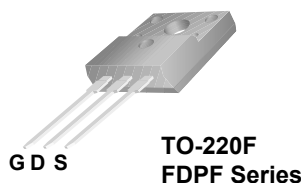
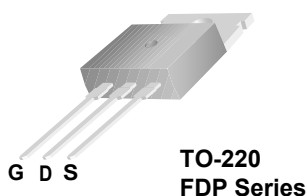
- $R_{DS(on)} = 0.22\Omega$ (Typ.) @ $V_{GS} = 10V$, $I_D = 10A$
- Low gate charge (Typ. 50nC)
- Low C_{rss} (Typ. 27pF)
- Fast reverse recovery switching of built-in diode
- Fast switching
- 100% avalanche tested
- Improve dv/dt capability
- RoHS compliant



Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advance technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switching mode power supplies and active power factor correction.



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FDP20N50F	FDPF20N50FT	Units
V_{DSS}	Drain to Source Voltage	500		V
V_{GSS}	Gate to Source Voltage	±30		V
I_D	Drain Current	-Continuous ($T_C = 25^\circ\text{C}$)	20	20*
		-Continuous ($T_C = 100^\circ\text{C}$)	12.9	12.9*
I_{DM}	Drain Current	- Pulsed (Note 1)	80	80*
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	1110	mJ
I_{AR}	Avalanche Current	(Note 1)	20	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	25	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	20	V/ns
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	250	38.5
		- Derate above 25°C	2.0	0.3
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300		$^\circ\text{C}$

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDP20N50F	FDPF20N50FT	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.5	3.3	$^\circ\text{C/W}$
$R_{\theta CS}$	Thermal Resistance, Case to Sink Typ.	0.5	-	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

Package Marking and Ordering Information $T_C = 25^\circ\text{C}$ unless otherwise noted

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP20N50F	FDP20N50F	TO-220	-	-	50
FDPF20N50FT	FDPF20N50FT	TO-220F	-	-	50

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$, $T_J = 25^\circ\text{C}$	500	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, Referenced to 25°C	-	0.7	-	$V/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 500\text{V}$, $V_{GS} = 0\text{V}$	-	-	10	μA
		$V_{DS} = 400\text{V}$, $T_C = 125^\circ\text{C}$	-	-	100	
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30\text{V}$, $V_{DS} = 0\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\mu\text{A}$	3.0	-	5.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}$, $I_D = 10\text{A}$	-	0.22	0.26	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 20\text{V}$, $I_D = 10\text{A}$ (Note 4)	-	25	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	2550	3390	pF
C_{oss}	Output Capacitance		-	350	465	pF
C_{rss}	Reverse Transfer Capacitance		-	27	40	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 400\text{V}$, $I_D = 20\text{A}$ $V_{GS} = 10\text{V}$ (Note 4, 5)	-	50	65	nC
Q_{gs}	Gate to Source Gate Charge		-	14	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		-	20	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 250\text{V}$, $I_D = 20\text{A}$ $R_G = 25\Omega$ (Note 4, 5)	-	45	100	ns
t_r	Turn-On Rise Time		-	120	250	ns
$t_{d(off)}$	Turn-Off Delay Time		-	100	210	ns
t_f	Turn-Off Fall Time		-	60	130	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	20	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	80	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _{SD} = 20A	-	-	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 20A dI _F /dt = 100A/μs (Note 4)	-	154	-	ns
Q _{rr}	Reverse Recovery Charge		-	0.5	-	μC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L = 5\text{mH}$, $I_{AS} = 20\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 20\text{A}$, $dI/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

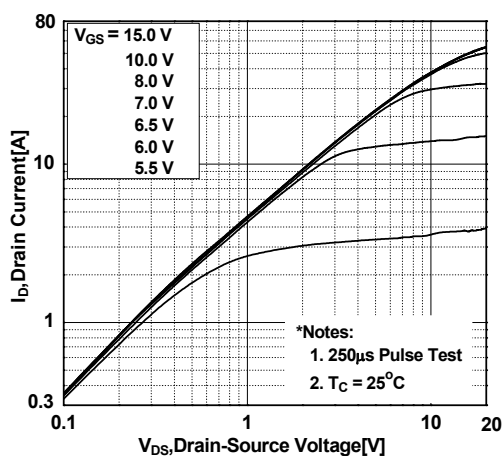


Figure 2. Transfer Characteristics

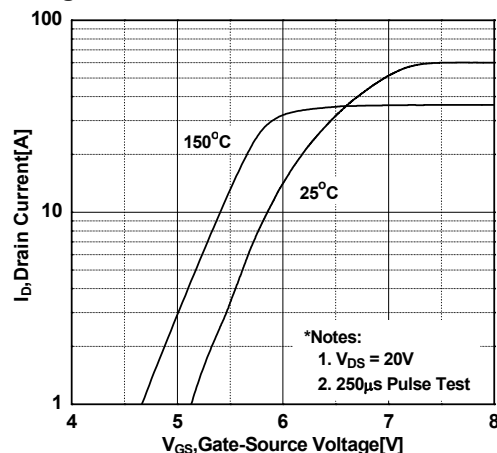


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

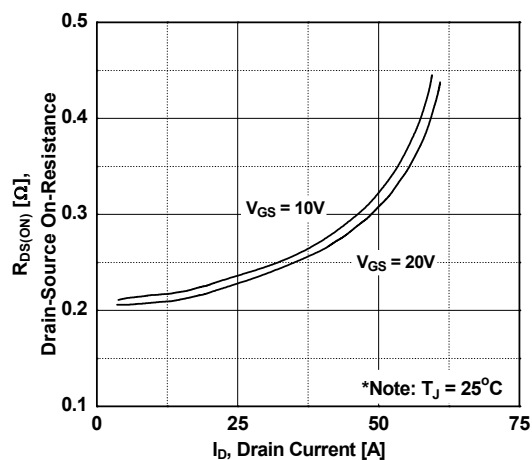


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

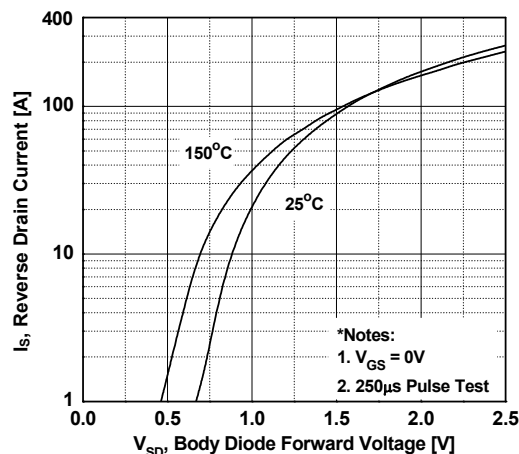


Figure 5. Capacitance Characteristics

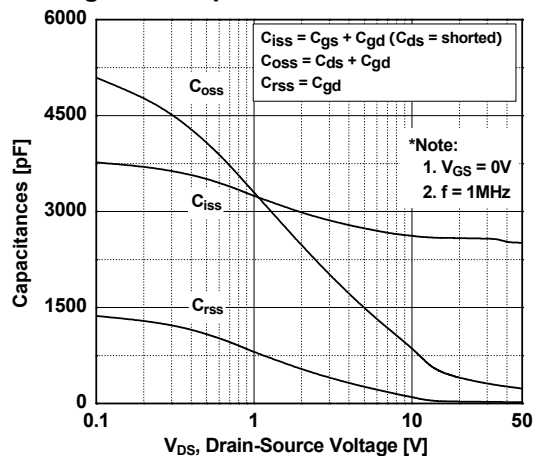
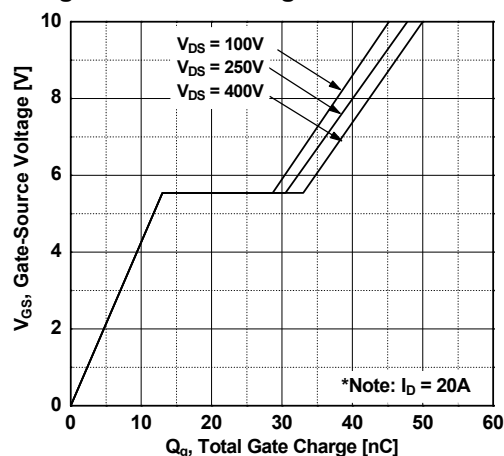


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

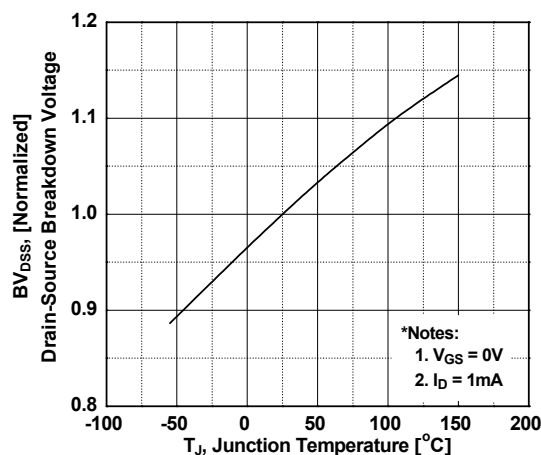


Figure 8. Maximum Safe Operating Area - FDP20N50F

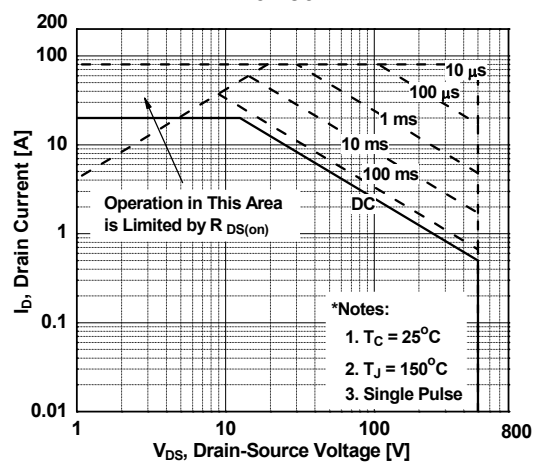


Figure 9. Maximum Safe Operating Area - FDPF20N50FT

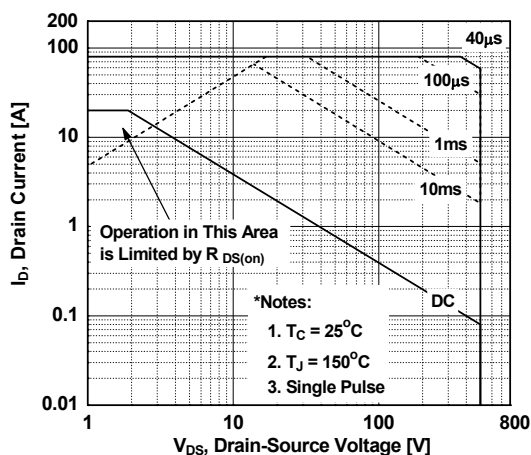


Figure 10. Maximum Drain Current vs. Case Temperature

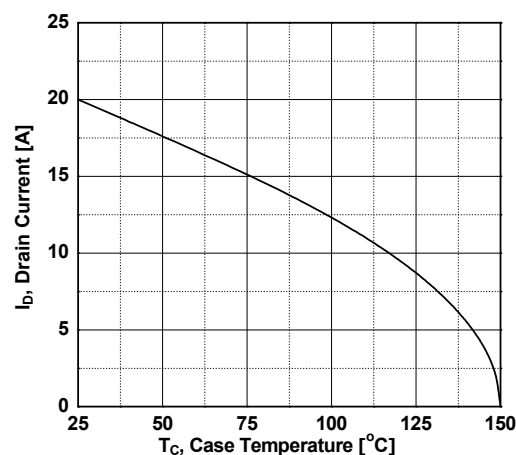
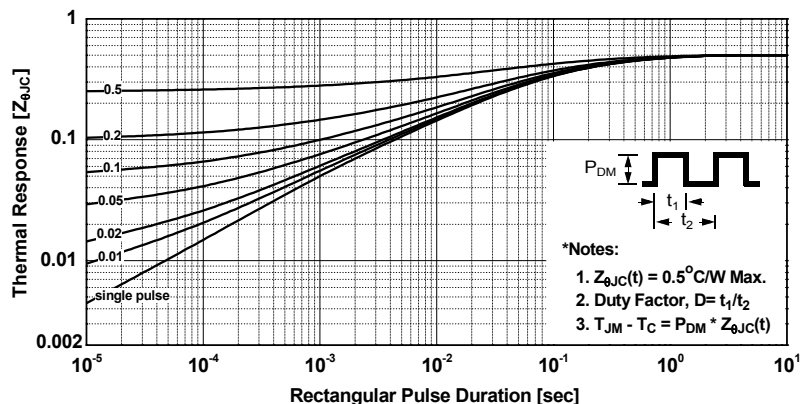
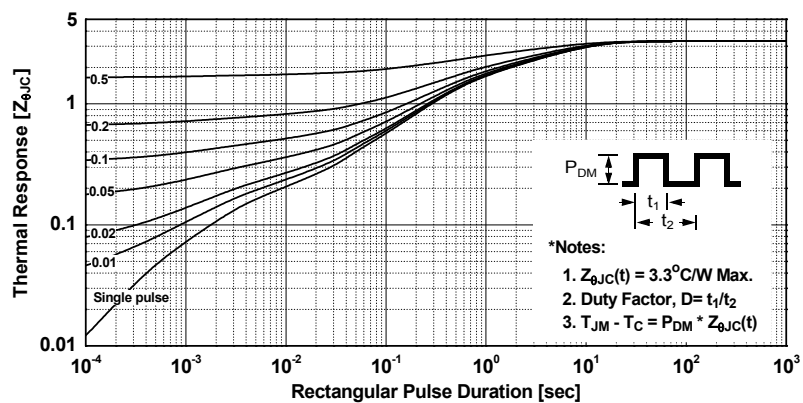


Figure 11. Transient Thermal Response Curve - FDP20N50F

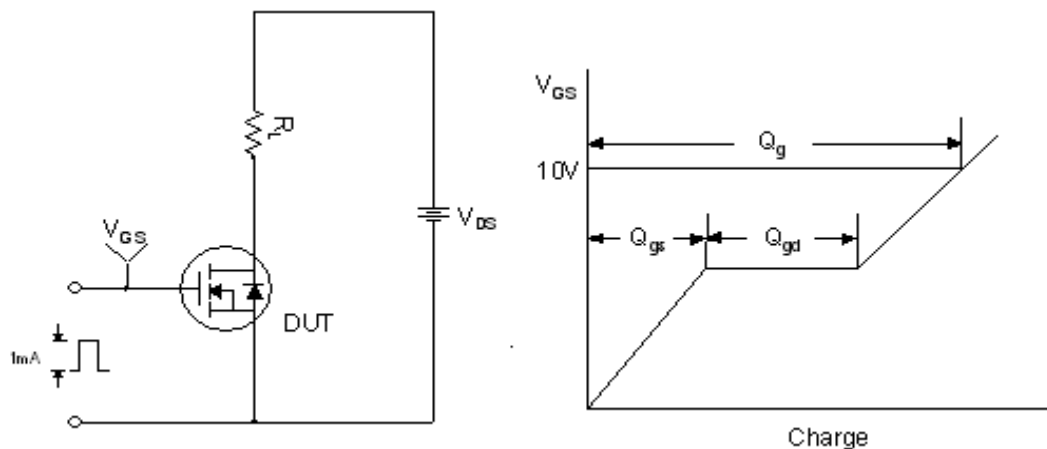


Typical Performance Characteristics (Continued)

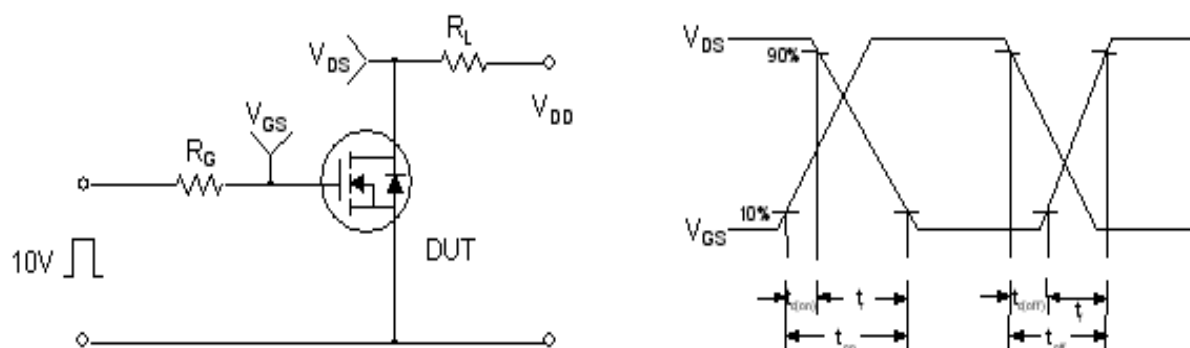
Figure 12. Transient Thermal Response Curve - FDPF20N50FT



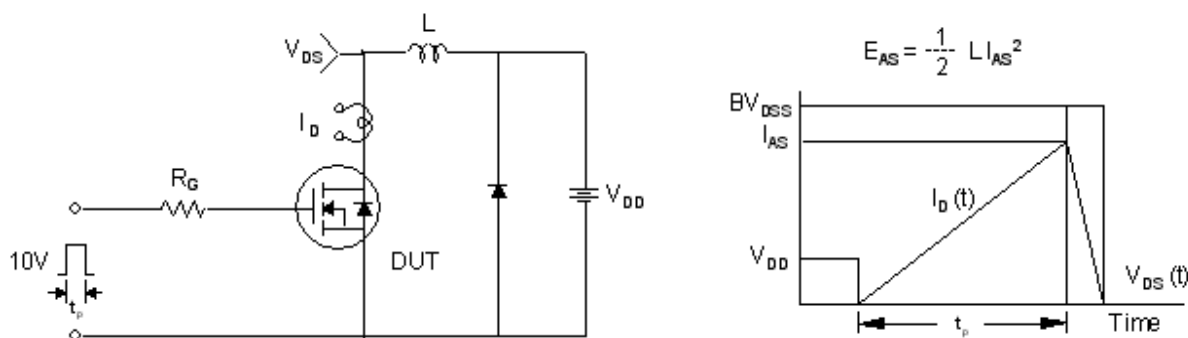
Gate Charge Test Circuit & Waveform



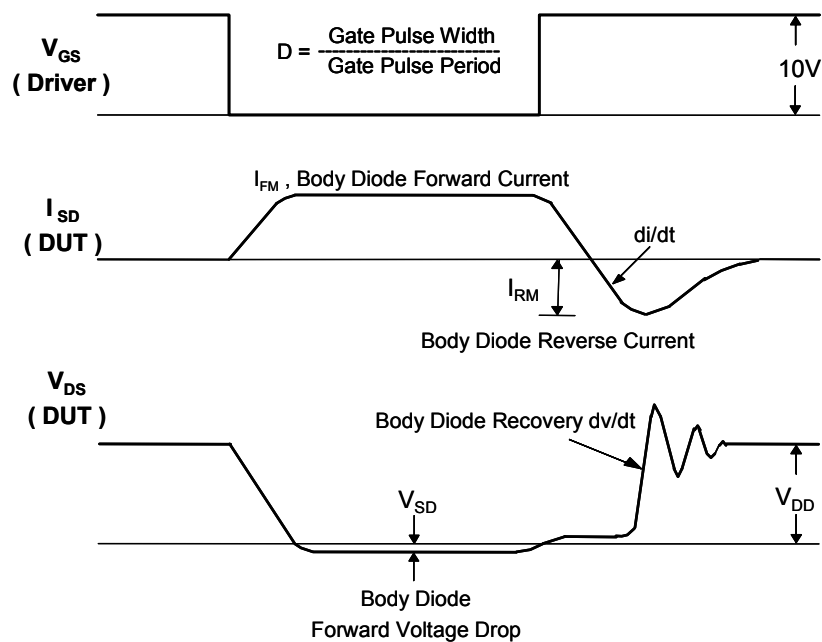
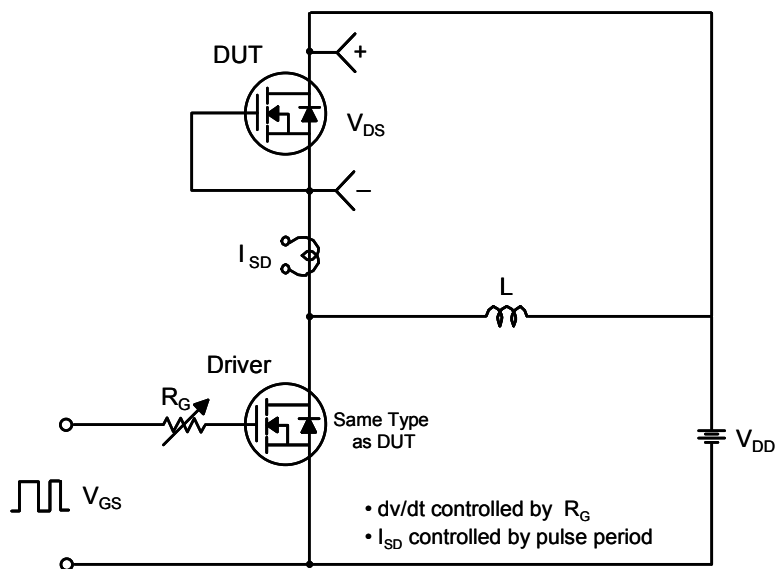
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

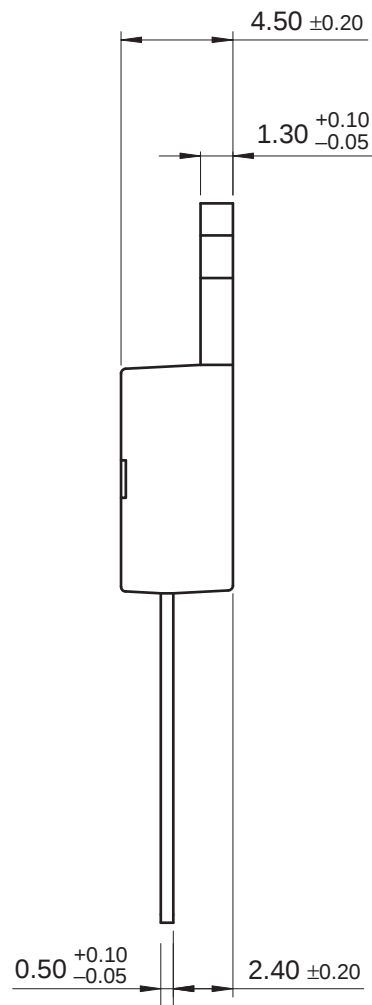
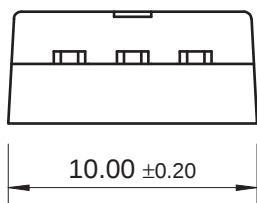
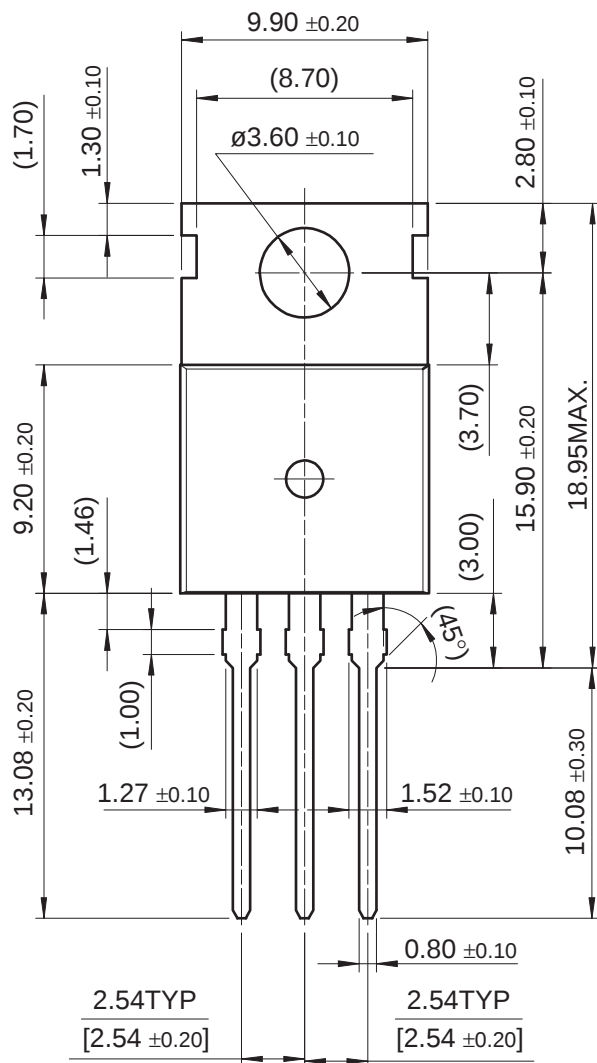


Peak Diode Recovery dv/dt Test Circuit & Waveforms



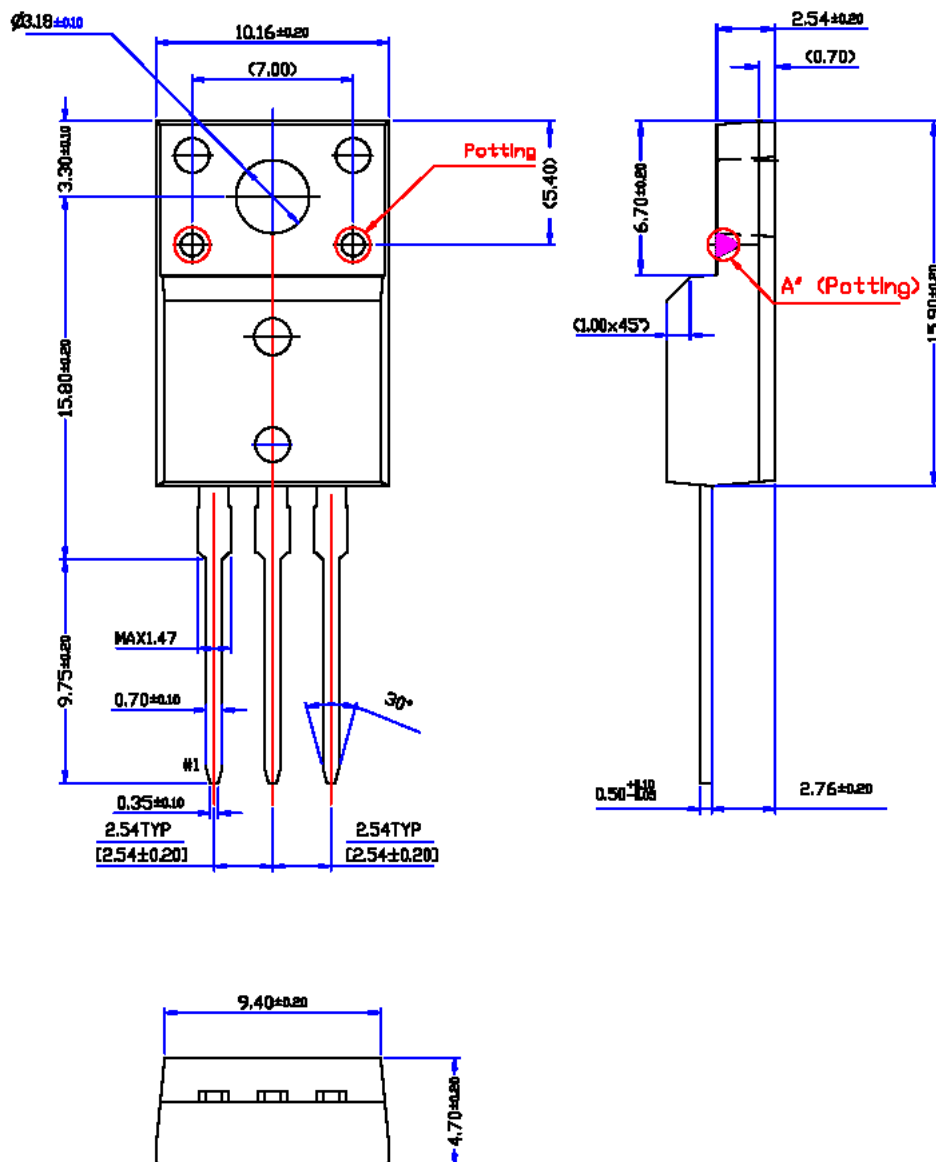
Mechanical Dimensions

TO-220



Mechanical Dimensions

TO-220F Potted



* Front/Back Side Isolation Voltage : AC 2500V

Dimensions in Millimeters



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